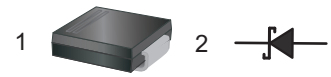
FEATURES

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMC



Top View
Marking Code: SS520
Simplified outline SMC and symbol

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Absolute Maximum Ratings and Electrical characteristics

Parameter	Symbols	SS520	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	200	V
Maximum RMS voltage	V_{RMS}	140	V
Maximum DC Blocking Voltage	V_{DC}	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	150	A
Max Instantaneous Forward Voltage at 5 A	V_F	0.85	V
Maximum DC Reverse Current T_a = 25°C at Rated DC Reverse Voltage T_a =100°C	I_R	1.0 50	mA
Typical Junction Capacitance (1)	C_j	400	pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	35	°C/W
Operating Junction Temperature Range	T_j	-55 ~ +150	°C
Storage Temperature Range	T_{stg}	-55 ~ +150	°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

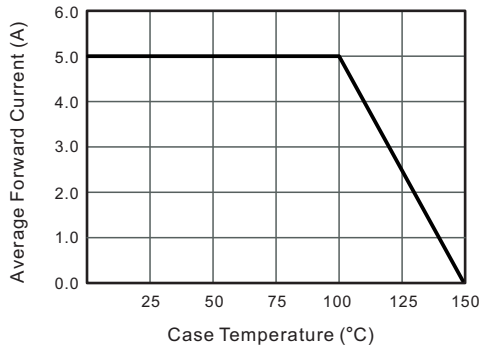


Fig.2 Typical Reverse Characteristics

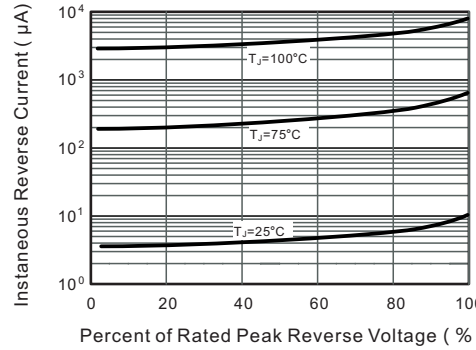


Fig.3 Typical Forward Characteristic

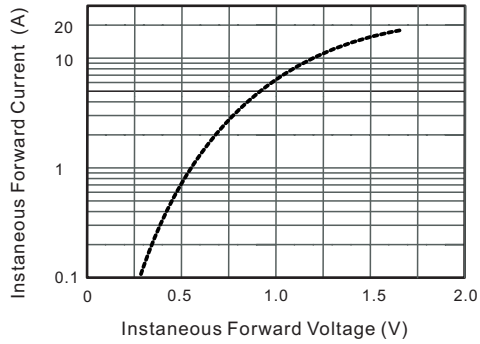


Fig.4 Typical Junction Capacitance

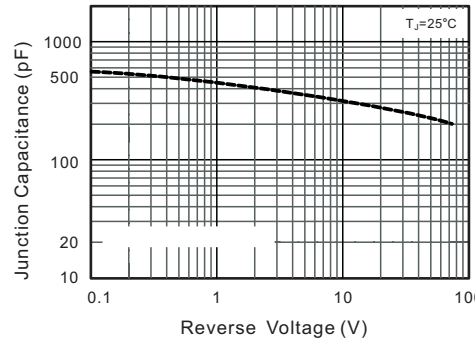


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

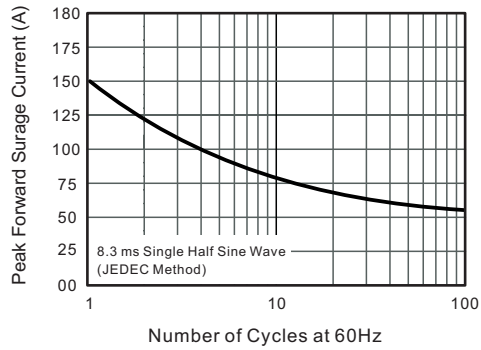
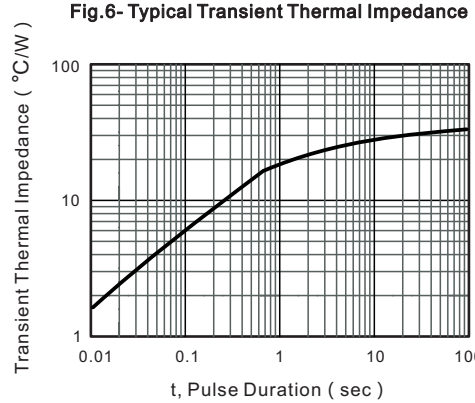


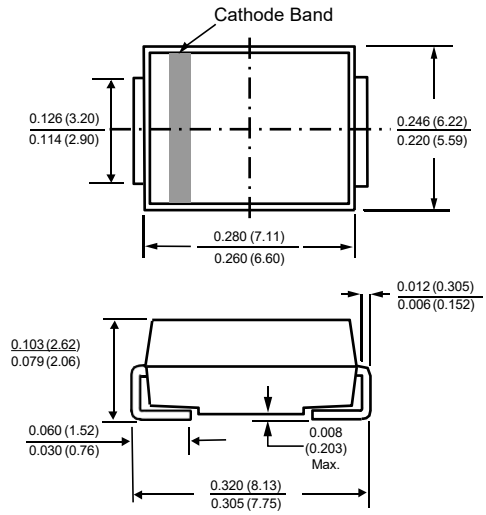
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMC (DO-214AB)



Mounting Pad Layout